

COPPER PASTE

Patent Number: JP3176906
Publication date: 1991-07-31
Inventor(s): SUGIMOTO FUMIO; others: 02
Applicant(s): FURUKAWA ELECTRIC CO LTD:THE
Requested Patent: ☐ JP3176906
Application Number: JP19890315611 19891205
Priority Number(s):
IPC Classification: H01B1/22; C09D5/24
EC Classification:
Equivalents:

Abstract

PURPOSE: To improve the flatness and resolution of a film to be formed, to prevent the reduction of film thickness due to stage difference of a substrate and to prevent the generation of a void, by mixing the spherical copper powder and the dendritic copper powder in a predetermined ratio for use.

CONSTITUTION: Copper paste is mainly composed of copper powder and resin group binder. The copper powder is made of the mixture powder which consists of spherical copper powder and dendritic copper powder, and the ratio of the spherical copper powder against the whole of the copper powder is 10-60weight%. Since isotropic molten copper is mixed besides anisotropic dendritic copper powder, excessive thixotropy is restricted. Furthermore, the reduction of film thickness due to a stage difference part, where a flow quantity of ink during printing is increased, is restricted by the lubricating property of the spherical copper powder. As a result, the generation of bleeding at the time of printing this copper paste is restricted, and flatness of the film is improved to prevent the generation of a void.

Data supplied from the esp@cenet database - I2

BEST AVAILABLE COPY